

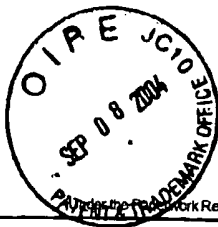


PTO/SB/08a/b (08-03)
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)		Complete If Known			
		Application Number	09/866,463-Conf. #4951		
		Filing Date	May 24, 2001		
		First Named Inventor	Gregory J. Wilson		
		Art Unit	1742		
		Examiner Name	D. R. Valentine		
Sheet	1	of	2	Attorney Docket Number	291958157US3

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	† ⁴
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Examiner Signature	Donald R Valentine			Date Considered	10/19/04	



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Sheet	2	of	2	Attorney Docket Number	291958157US3

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NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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¹ Applicant's unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

Examiner Signature	<i>Donald R. Valentine</i>	Date Considered	10/19/04
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